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Claim (currently amended): The sensing sensor device of claim 36 claim 1 wherein said fixed electrode is formed as a conductive layer on said substrate.

Claim (currently amended): The sensing sensor device of claim 1 wherein said sensor comprises is at least partially formed of a cap layer on said substrate.

Claim & (currently amended): The <u>sensing sensor</u> device of claim & wherein said cap layer includes portions defining a diaphragm of said sensor.

Claim (currently amended): The sensing sensor device of claim wherein said active circuitry is integrally fabricated in said substrate. with said sensor.

Claim 7 (currently amended): The <u>sensing sensor</u> device of claim 4 wherein said cap layer is formed of monocrystalline silicon.

Claim & (currently amended): The sensing sensor device of claim wherein said cap layer is boron doped silicon.

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Claim (currently amended): The <u>sensing sensor</u> device of <u>claim 30 claim 1</u> wherein said fixed and moveable electrodes define an interior volume therebetween and <u>a</u>

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surface cavity in portion of said substrate defines define a displacement cavity in communication with said interior volume.

Claim 16 (currently amended): The sensing sensor device of claim 36 claim 1 wherein said fixed electrode includes a main electrode and at least one reference electrode.

Claim 1 (currently amended) The sensing sensor device of claim 1 wherein said sensing device is entirely implanted within said human body and is operating to measure the physiologic parameter within said human body. —monolithic.

Claim 12 (currently amended): The sensing sensor device of claim 1 further comprising a cap layer formed over said substrate.

Claim 13 (currently amended): The sensing sensor device of claim 12 wherein said cap layer includes a portion defining a moveable electrode of said sensor.

Claim (currently amended): The sensing sensor device of claim 1/2 wherein said cap layer is conductive.

Claim 16 (currently amended): The sensing sensor device of claim 12 wherein

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Claim 35 (currently amended): The sensing sensor device of claim 32 wherein said housing is of a non-rigid material.

Claim 34 (currently amended): The <u>sensing sensor</u> device of claim 32 wherein said housing is a <u>plastic material</u>. of <u>plastic</u>.

Claim 35 (currently amended): The sensing sensor device of claim 32 wherein said housing comprises a recess providing intimate access to the sensor. is soft.

Claim 38 (new): The sensing device of claim 1 wherein said sensor is a capacitive sensor having a fixed electrode and a moveable electrode.